

18<sup>th</sup> November 2009



#### AVIONICS AND SURVEILLANCE DIVISION

End-to-end avionics and covert surveillance solutions



#### DEFENCE SYSTEMS DIVISION

Critical technology for network centric operations



#### MISSION SYSTEMS DIVISION

Complete 'nose to tail' refuelling and 'wingtip to wingtip' mission systems capability



#### AVIATION SERVICES DIVISION

Operates, modifies and maintains more than 150 fixed and rotary wing aircraft around the world

## Reducing Cost, Size and Mass of MPAR Radar Arrays

# Cobham Overview

## Summary

### Enterprise Started in 1934 by Sir Alan Cobham

- An innovative aviation pioneer – Aug 1926 – England to Australia & back; refueling - 1933
- 1939 – Refueling aircraft from aerial tankers
- RAF & US Army Air Force began refueling trials in the last year of WWII



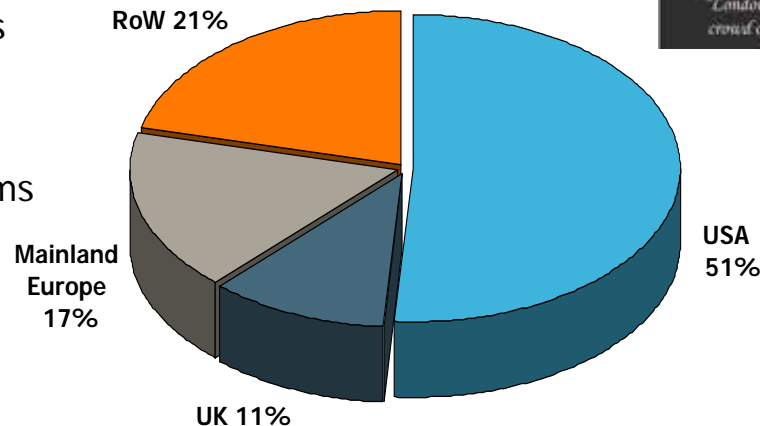
*"London, 1926, Sir Alan Cobham landing on the river Thames in front of a crowd of 1 million people after flying 26,000 miles to Australia and back."*

### Four Divisions Operating on Five Continents with 12,000 Employees Worldwide

- **Cobham Defense Systems (CDS)**
- Cobham Avionics & Surveillance
- Cobham Mission Systems
- Cobham Aviation Services

### Major Operations

- Defense Electronic Systems
- Antennas
- Avionics and Surveillance
- Communications
- Homeland Security



*Alan Cobham relied on meteorological office reports in the 1920s and 30s*

# Cobham Overview

## Cobham Sensor Systems

### Technologies/ Products/ Services

- Active microwave
- Passive microwave
- Electronic warfare antennas
- Communication, navigation & identification (CNI) antennas
- Radar antennas – fire control radar, weather radar, synthetic aperture radar
- Radomes and advanced composites
- High-precision positioners

### Facts

- Facilities in the USA, Mexico, Sweden
- President: Steve Schaefer

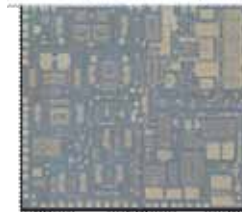
### Markets

- Tactical Radar & Communication
- Satellite Communication
- Tactical Missiles
- Electronic Warfare
- Missile Defence
- Space Systems

### Business Units

- Sensor Electronics
- Microwave Electronics
- Microwave Components
- Advanced Programs and Technology

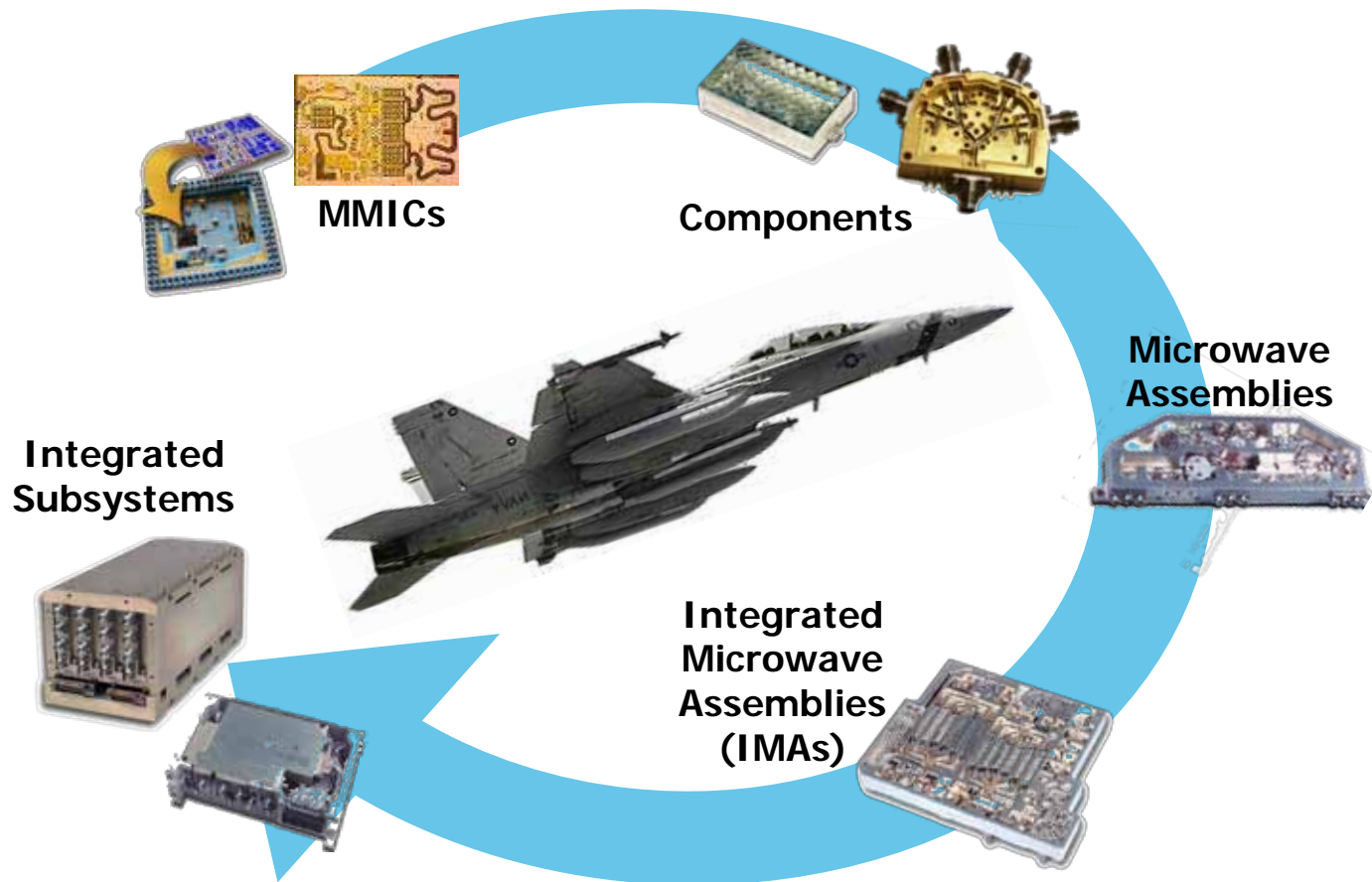
T/R MMIC, 15 sq. mm



135-mm on-chip gate width;  
> 1000 pF MIM capacitance  
0.5-µm pHEMT

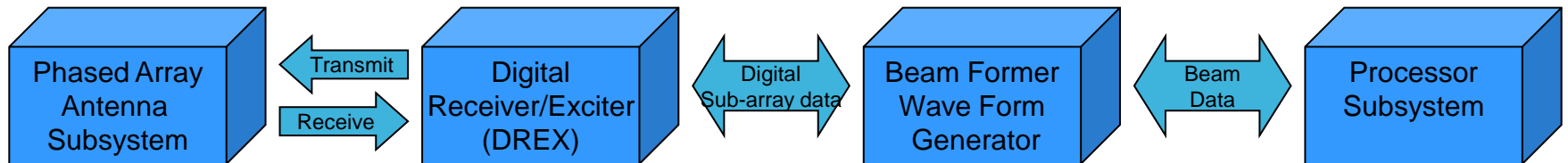
# Product Integration Strategy

Strong component foundation enables the development of integrated products resulting in higher performance, smaller size, and lower cost



# Radar Subsystems Roadmap

Radar architecture has four major subsystems



- L, S, X, and Ku band T/R MMIC's
- T/R module packaging
- Array architecture developed

**2004**



- 256 element arrays
- 1024 element array
  - X-band
- Full DREX 32 channel subsystem delivered
  - S-Band

**2009**



- Complete Panel building blocks for S, X, and Ku band arrays
- Partner for platform deliveries
- DREX building blocks at S and X band
  - Low cost architectures

**2013**

# What can Cobham Contribute to MPAR?

- Architecture/implementation cost trade off studies
  - Cobham is not wedded to any particular technology; we use all types of technology
    - Technology choices based on best solution
  - We use multiple foundries for MMIC development, both within Cobham and outside
  - We manufacture hardware so we have to accurately estimate costs to survive in a competitive environment. *95% of the work (including development) we do is firm fixed price.*
  
- Demonstration hardware
  - We have similar hardware that can be adapted to MPAR needs
    - X-band phased array antenna subsystem
    - Many highly integrated custom MMICs developed for L, S, C, X and Ku-band radars, including specifically for MPAR
    - S-band Digital Receiver Exciter (DREX)
    - Large number of components developed for other radar programs

# What can Cobham Contribute to MPAR?

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- Strong technology in core RADAR areas
  - MSAG and HVMSAG are Cobham advantages
  - Smallest MMICs in industry, results in lower costs
  - Lowest thermal impedance MMICs -- simplifies packaging and cooling
  - Capability includes MMIC, digital, antenna, and T/R functions
- IR&D Support
  - We have internal IR&D programs for S-band and X-band development that need input from MPAR

# Requirements for a LOW COST Phased Array Supplier



- Highly Integrated Custom MMICs
  - MMICs 20% or higher percentage cost of the array
  - Innovative designs required to achieve element spacing. Older approaches with “brick” T/R modules will not meet cost goals
  - Highly efficient designs required to achieve thermal performance and reliability
- Low Cost Packaging Approaches
- Innovative Antenna Technologies – Dual Polarity designs
- High Volume Manufacturing capability
  - Automation for assembly and test
- Open Architecture
  - Willingness to work with open and non-proprietary interfaces
  - Allows technology insertion, competition; not hostage to system supplier
- Scalable Design
  - Allows arrays of any number of panels to be made



## Tile Design

- Scalable
- 256 element building block
- Highly integrated custom MMICs for optimum performance, layout, & lowest cost
- Horizontal layout of T/R electronics instead of vertical “brick” T/R Modules
  - Allows use of **single, low cost PCB (printed circuit board) for 16 elements** ASA (analog subarray) building block
  - **Low cost protective coatings** over MMICs instead of hermetic packaging
  - Embedded passives in PCB
  - **Lower cost than T/R module** approach
  - Radiator assembly with various polarity
  - **Air cooled**
- Integrated FPGA controller and DC-DC converter

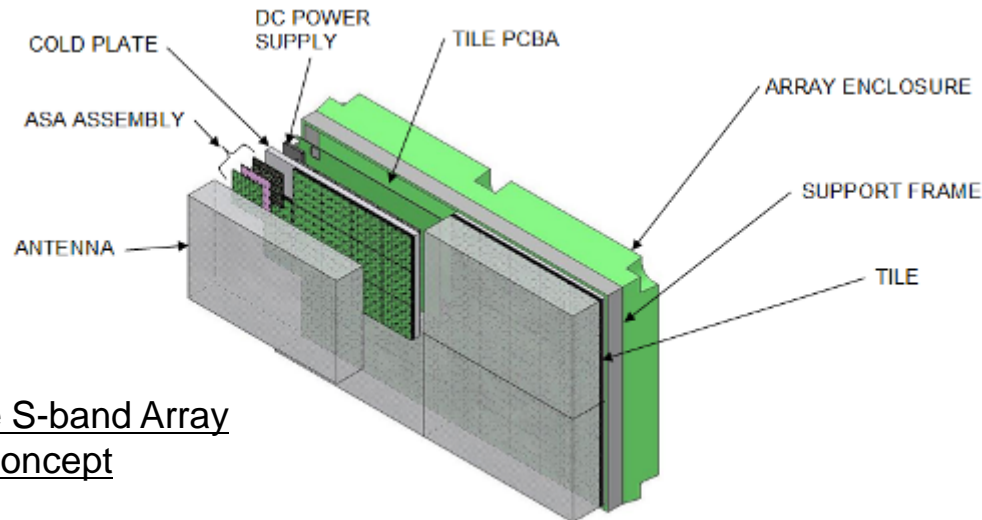
# X-band Phased Array Antenna (IR&D)

## Subsystem Key Specification Summary



§ DC Voltage	28 V – to 300 V option
§ DC Power Consumption	< 1 kW
§ Tile Size	256 elements
§ Tile Area	< 100 sq. in.
§ Depth	4.0”
§ Weight	~3.5 kg (includes all DC converters)
§ Transmit Polarization	Circular or linear options
§ Receive Polarization	Circular or linear options
§ Thermal	Air Cooled
§ Interface	Open Architecture
§ Calibration	<i>Ability to calibrate every element individually</i>

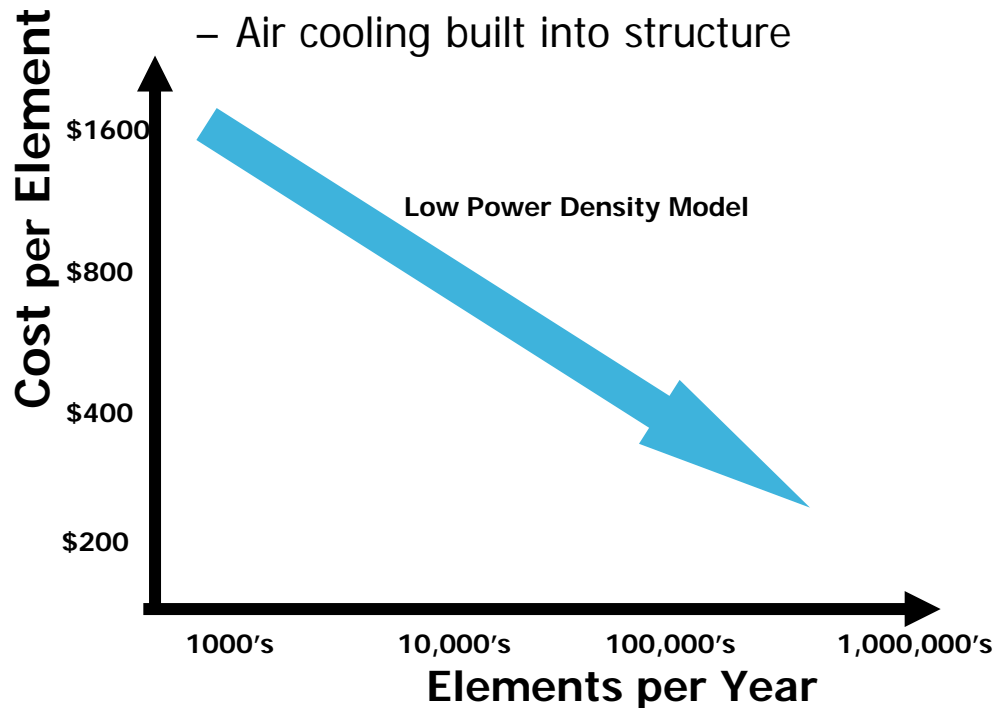
- Leverage X-band strength and benefits of the larger array spacing at S-band into a low cost building block
  - Scalable
  - Dual Polarity
  - Integrated MMIC chipset
  - *Air cooling to 50 W per element*; Liquid cooling to 200 W + (10% duty cycle)
  - Integrated Calibration approach
  - Integrated Beam steering controller
  - Automated surface mount assembly maintaining thermal performance



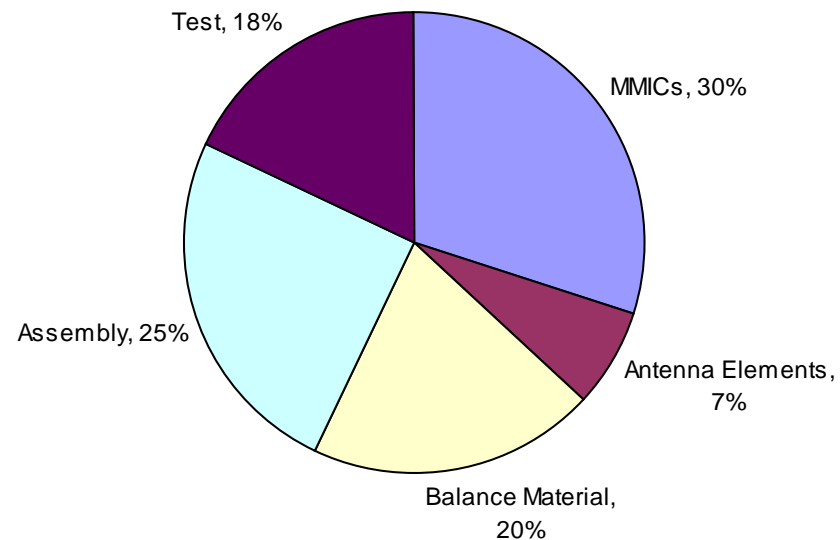
Scalable S-band Array  
Concept

# Cost Model - Inclusive of All Array Functionality **COBHAM** (not just T/R module cost)

- X-band model shown; S-band: lower cost packaging & lower cost MMIC processes
- Quantity required to reduce per element cost
- Must leverage building blocks across multiple programs
  - Must be considered when optimizing for one frequency band or requirement
- Innovative MMIC technologies, packaging, thermal control necessary
  - Design into 6" or larger wafers for high quantity parts
  - Air cooling built into structure



Approximate Cost Breakdown  
(10K element qty's)



# Technology Tradeoffs

## Device Type:

- GaAs - PHEMT - MSAG - HVMSAG – HBT - GaN – SiC - SiGe - LDMOS - CMOS
- Cobham has experience with all of the above

## Specification Trades:

- Power per element                      -- Noise figure per element
- PAG/T is a one figure of merit for a radar array: **Power \* Antenna Area \* antenna Gain / noise Temperature**. PAG/T is proportional to the cube of the number of elements
- Polarization choices: dual linear only vs. dual linear plus dual circular, receive simultaneous polarization, etc.

## Example of Trades:

- SiGe amplifiers are less expensive than GaAs but higher noise figure. **Higher noise figure means more elements are required to make the same PAG/T**. Conversely, pHEMT is more expensive than MESFET but lower noise figure. The trade has to be done at the system level.
- Higher power amplifiers = fewer number of elements; total DC power increases & cost per PA MMIC increases (**PA is the most expensive MMIC**).

# HVMSAG MMICs COST LESS Today

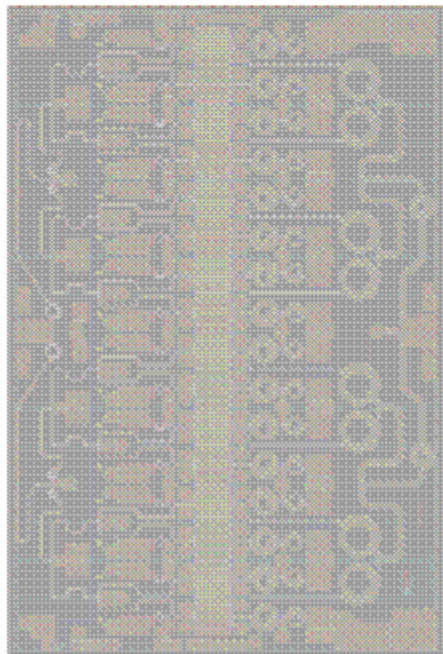


<b>Material Cost Comparison</b>	<b>HVMSAG</b>	<b>GaN on SiC</b>
Power Density (W/mm; 28 V)	1.8	6
Power Density Ratio'ed to HVMSAG	1	3.3
Starting Material Cost (\$)	700	7000
Wafer Diameter (mm)	100	100
Starting Material Cost (\$ / sq. mm)	\$ 0.11	\$ 1.10
Cost (\$ / sq. mm) Ratio'ed to HVMSAG	1	10
<b>Cost Ratio / Power Ratio</b>	<b>1</b>	<b>3</b>

High Power L,S, and C band Radar applications

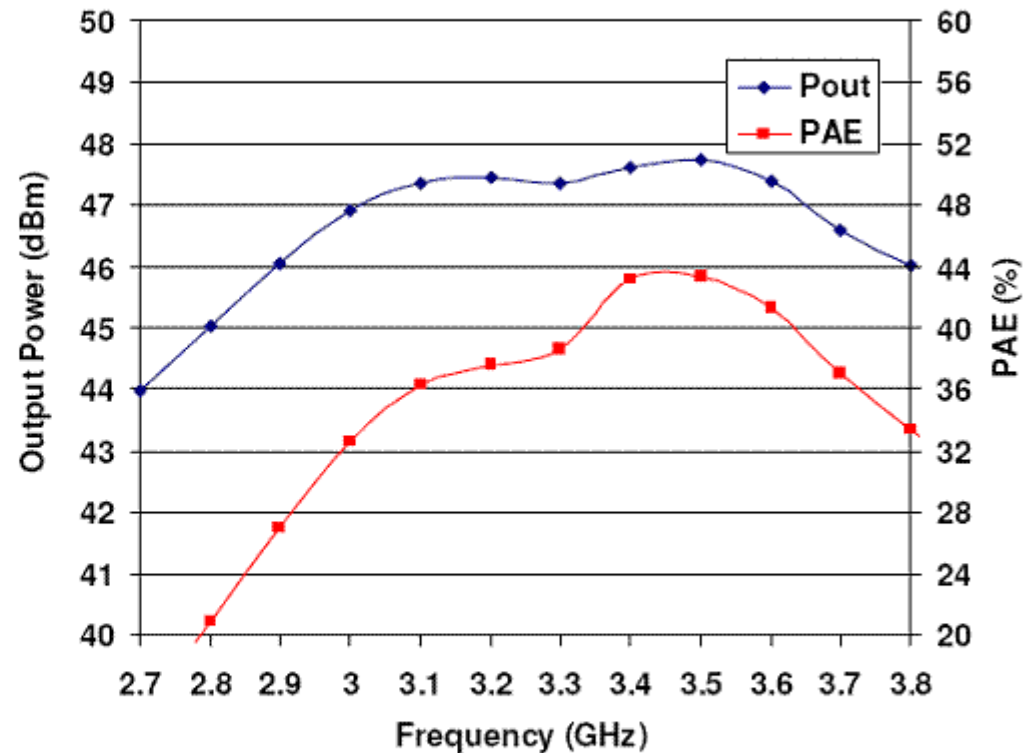
# MESFET High Power Amplifier

- 50W, single stage
- 3 – 3.6 GHz
- 28V Supply
- 30-44% PAE
- 2mil GaAs



**Chip Size**  
7500 x 5000um

*Fully on-chip matched PA*



# MPAR Pricing Targets, MMIC Constraints

Target Price: \$50k / sq. meter of aperture

- Equates to \$130 / element at S-Band
- Element price includes aperture structure, cooling, radiators, radome, power conditioning, logic, beamformers and T/R modules
- T/R modules will make up 50% of this budget
  - < \$60-70 / module
  - MMIC Content will be largest portion of the T/R module Cost
  - PA (power amplifier) is the most expensive function
    - HVMSAG is the most cost effective technology today for S-band power MMICs in the 2 - 60 W range
    - GaN technology and cost are improving for the solution

## MPAR Requirements Driving Cost

- Variable Polarization: combined linear & circular capability roughly **doubles** the MMIC area
- Power. PA MMIC area roughly proportional to power; drives heat removal techniques. Passive matching networks require more area than transistors.

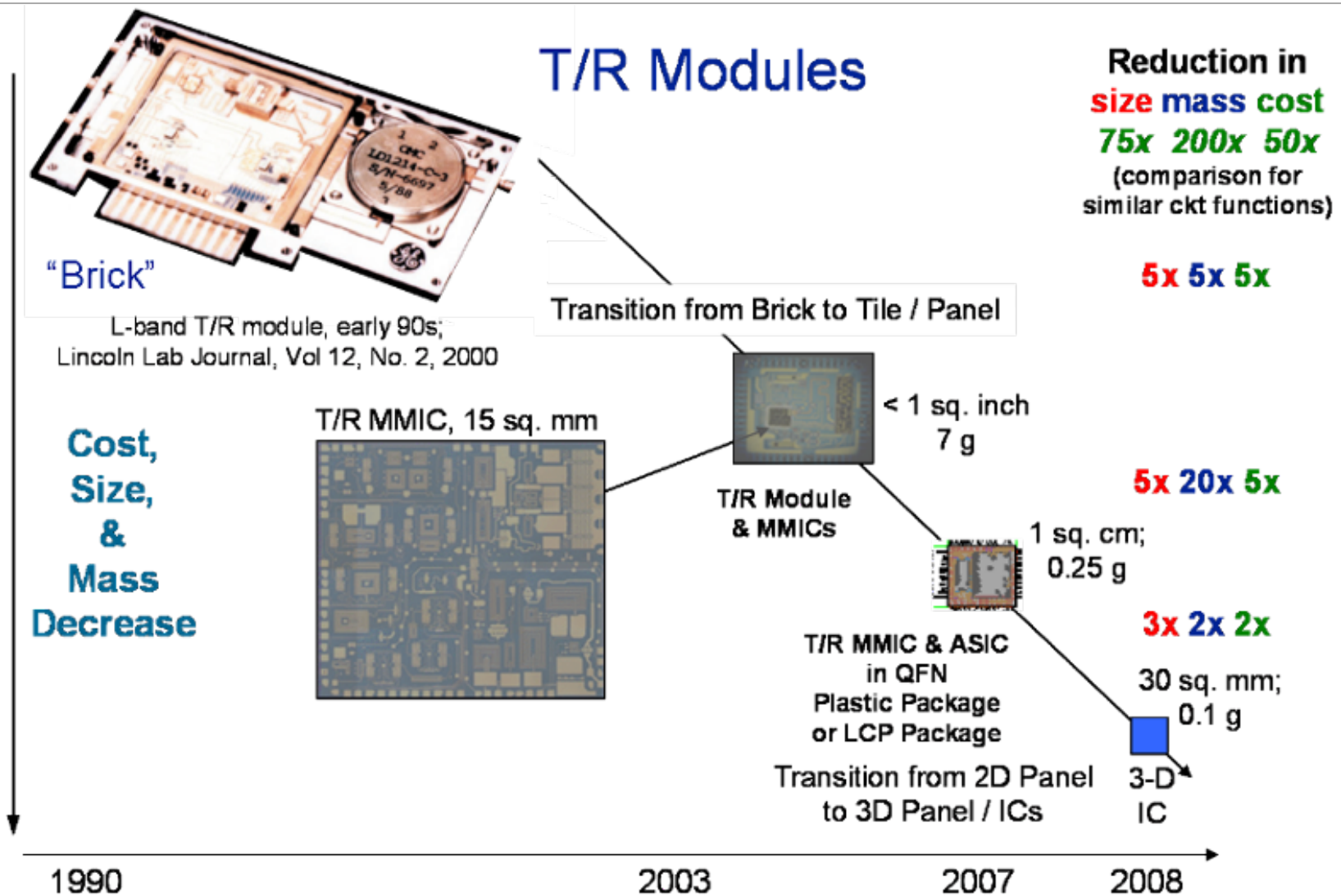


# MMICs Developed for S-band

- Custom S-band MMICs developed specifically for phased array radars
- Suitable for dual polarization application as needed for MPAR
- Small die area lowers cost
- MSAG (multifunction self aligned gate) and HVMSAG (high voltage MSAG) are two Cobham specific technologies
- MSAG, HVMSAG/HEMT addresses *> 80% of the Military MMIC Market*
- *3X to 5X lower MMIC cost* compared to GaN & SiC today
  - *High efficiency, gain, linearity & reliability*
  - Supports miniature, *low cost, highly integrated* T/R MMICs

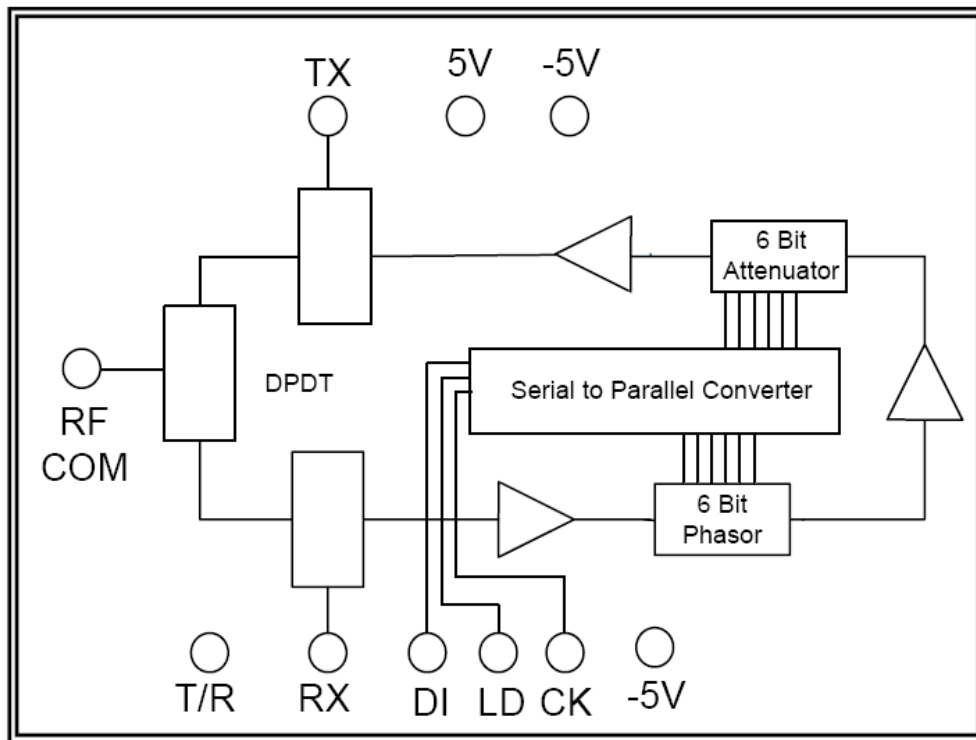
- PCB-Based Assembly
  - Surface Mount Construction, Air-Cooled
- Off-shore Assembly & Plastic Packaging of untested MMICs
  - IC Yields > 85%
- Integration of MMICs where it makes sense
  - Will not impact yield
- Total IC area < 60 sq mm
  - Tx Power to 5 W or higher at element output
  - High Voltage Process, HVMSAG or GaN

# Reducing Cost, Size, and Mass



# S-Band Common Leg Circuit (CLC)

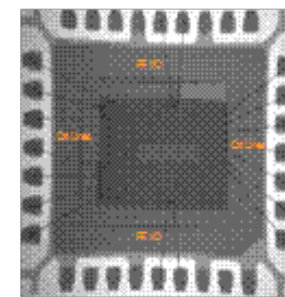
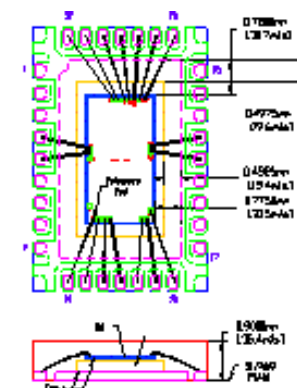
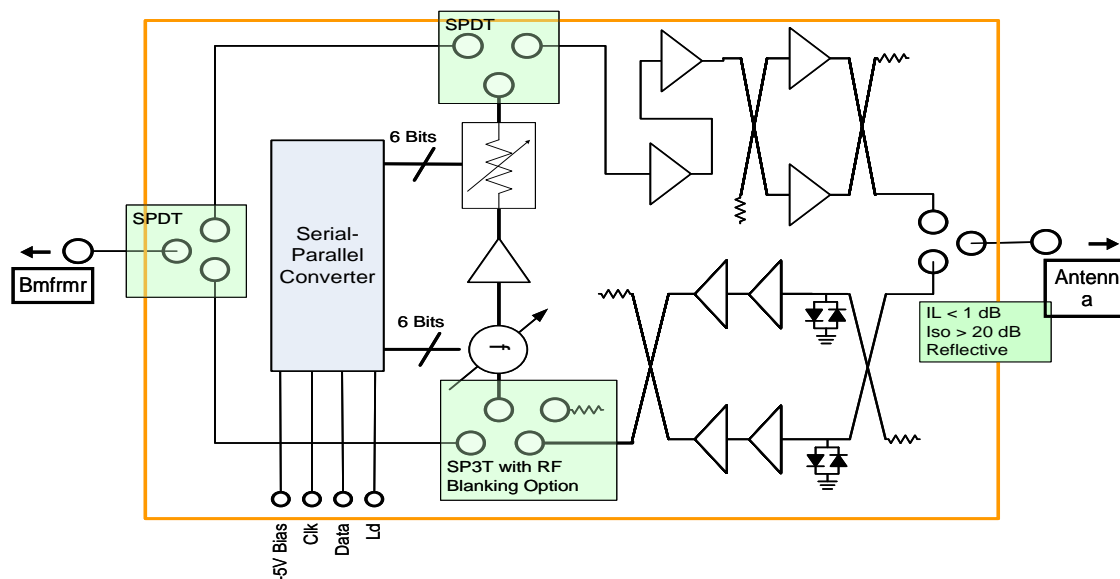
Phase shifter, attenuator, amplifiers, S-to-P converter, switches



~ 10 sq. mm

# S-band Radar Single Chip T/R Element

- Single chip solution
- HVMSAG process enables integration
  - Integrated control functions with RF functions
  - Competing technologies require multi-chip solutions
- Eliminates significant packaging and assembly labor costs
- Low cost solution



Simple T/R Module

# S-Band DREX (Digital Receiver-Exciter)

- Distributed Radar Application
- 4 synthesizers, 32 T/R channels
- Expandable to arbitrary number of channels
- Extremely low phase noise
- *Synthesizers have uncorrelated phase noise for even lower system level phase noise*
- Translates from digital signals to RF signal & vice versa
- Very good phase stability vs. time between channels



Low cost S-band DREX  
Multi-channel concept

## Low Cost S-Band DREX

- RF & IF bandwidth requirements significantly simplify performance requirements
- Move from modular, hermetic design approach to fully integrated single board design
- Multiple Channels per board – target 8; integrated A/D, D/A and FPGA on board

- Cobham -- has extensive phased array radar experience
- Legacy and IR&D programs are directly applicable to MPAR requirements
- Is positioned to make cost effective phased array radar hardware
- Has made significant investments in phased array radar technology
- Cobham requests MPAR inputs to influence its IR&D projects
- What can we do for you?

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